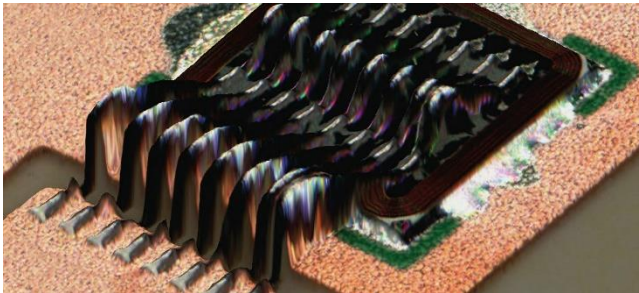


Press Release

Viscom presents advantages of 3D bond inspection at electronica

Hanover, Germany, November 2018 – electronica, hall A3, stand 642 –
With a wide range of inspection systems and camera modules, Viscom AG is offering outstanding solutions for fast, high-precision wire bond production inspections. At the electronica trade show in Munich from November 13-16, visitors can experience firsthand what 3D measurement contributes to product quality in this field.



The 3D inspection procedures which have long been standard at Viscom in the areas of optical inspection and X-ray inspection are now being used in

quality assurance for wire bonds as well, and can be used to determine loop heights very accurately, for example. In order to demonstrate for the first time at Viscom's electronica stand how 3D measurement results contribute to better inspection for defects in these products, a machine of the variably configurable type S6056BO was equipped with a new camera module. Designed specifically to handle the requirements of wire bond inspection, the module is based on the technologically proven 3D AOI modules XM and XMplus, which are used very successfully around the globe in the S3088 *ultra gold* und S3088 *ultra chrome* systems.

Bonds are used as jumpers in power electronics, for example. This is why they are integral parts of the ever-evolving storage batteries in the electromobility sector, among other things. As quality is particularly relevant to safety in this area, high standards are set for comprehensive, reliable inspections in production. In the area of wire bond inspection, Viscom offers a diverse range of high-performance hardware that includes various transport solutions for a range of substrates and workpiece carriers as well

as intelligent software with adapted algorithms for reliable error/defect detection.

Captions:

01_3D view of thick wire bonds (DCB substrate), taken with the new camera module by Viscom for 3D bond inspection

02_The S6056BO bond inspection system by Viscom is ideally suited for high throughput and dual-track operation

About Viscom

Viscom AG develops, manufactures, and sells high-quality inspection systems. The portfolio encompasses the complete bandwidth of optical and X-ray inspections. In the area of assembly inspection for electronics manufacturing, the company is among the leading suppliers worldwide. Viscom systems can be configured specifically for each customer and can be interlinked. The company headquarters and manufacturing location is in Hannover, Germany. With a large network of branches, applications centers, service support points and representatives, Viscom is represented internationally. Founded in 1984, Viscom has been listed on the Frankfurt Stock Exchange (ISIN: DE0007846867) since 2006. For additional information visit: <https://www.viscom.de/>